

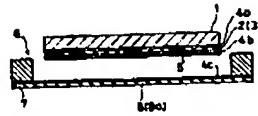
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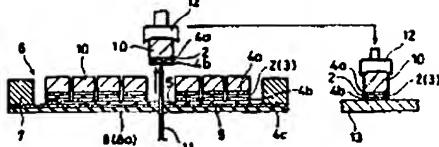
APPLICANT : HITACHI LTD;



INVENTOR : MIMATA TSUTOMU;



INT.CL. : H01L 21/78 H01L 21/52
TITLE : MANUFACTURE OF
SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To efficiently realize attachment of pellet with high reliability by dicing a wafer at each insulating plate in a state that the plate covers to the rear face of the wafer, and pellet-bonding inner leads, tabs or the mounting position of a package substrate in this state as it is.

CONSTITUTION: A semiconductor pellet 10 is cut in a state that an insulating plate 2 covers at the rear face side of a wafer 1 having a circuit forming face on one side face, and the pellets are bonded to the mounting positions in a state that the plate 2 covers. Thus, the pellet 10 having the plate on its rear face can be easily obtained, and a pellet bonding work can be efficiently performed with high reliability without addition of the mechanism of a device or large alteration of steps.

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